MA2J1150G

Silicon epitaxial planar type

For small power current rectification

■ Features

- S-mini type package, allowing high-density mounting
- High reverse voltage V_R

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	200	V
Maximum peak reverse voltage	V_{RM}	200	V
Output current	Io	200	mA
Repetitive peak forward current	I_{FRM}	600	μΑ
Non-repetitive peak forward surge current *	I _{FSM}	1	A
Junction temperature	Tj	150	°C
Storage temperature	$T_{\rm stg}$	-55 to +150	°C

Note) *: t = 1 s

Package

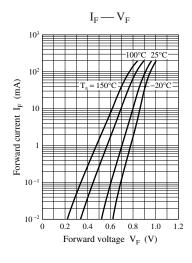
- Code
 SMini2-F3
- Pin Name
 - 1: Anode
 - 2: Cathode
- Marking Symbol: 1F

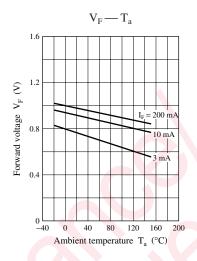
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

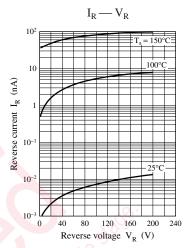
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 200 \text{ mA}$	7	55	1.2	V
Reverse current	I_R	$V_R = 200 \text{ V}$	00)		200	nA
Terminal capacitance	C_{t}	$V_R = 0 V, f = 1 MHz$	11.1	4.5		pF

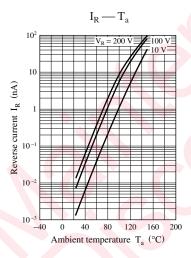
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

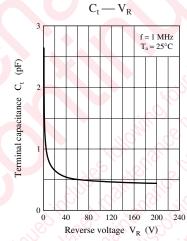
2. Absolute frequency of input and output is 3 MHz.

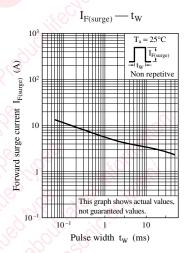






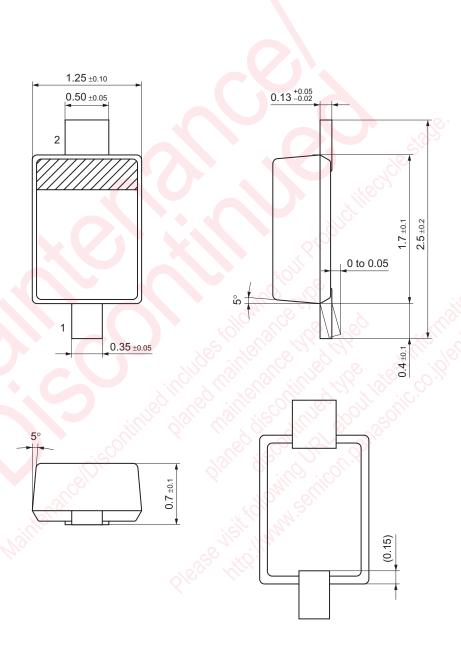






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SMini2-F3 Unit: mm



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